

**PATENT ASSIGNMENT**

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT

**CONVEYING PARTY DATA**

Name	Execution Date
Hiroyuki Kato	01/19/2007
Michihiro Sano	01/19/2007
Katsumi Maeda	01/24/2007
Hiroshi Yoneyama	01/29/2007
Takafumi Yao	02/06/2007
Meoung Whan CHO	02/06/2007

**RECEIVING PARTY DATA**

<b>Name:</b>	Stanley Electric Co., Ltd.
<b>Street Address:</b>	2-9-13, Nakameguro, Meguro-ku
<b>City:</b>	Tokyo
<b>State/Country:</b>	JAPAN

<b>Name:</b>	Tohoku University
<b>Street Address:</b>	1-1, Katahira 2-chome, Aoba-ku, Sendai-shi
<b>City:</b>	Miyagi
<b>State/Country:</b>	JAPAN

<b>Name:</b>	Tokyo Denpa Co., Ltd.
<b>Street Address:</b>	5-6-11, Chuo Ota-ku
<b>City:</b>	Tokyo
<b>State/Country:</b>	JAPAN

**PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	11509063

**CORRESPONDENCE DATA**

OP \$40.00 11509063

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NAME OF SUBMITTER:	Masao Yoshimura
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Total Attachments: 2
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**ASSIGNMENT**

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled:

**MANUFACTURE METHOD FOR ZnO BASED COMPOUND SEMICONDUCTOR CRYSTAL AND ZnO BASED COMPOUND SEMICONDUCTOR SUBSTRATE**

for which I/WE executed an application for United States Letters Patent concurrently herewith; or filed an application for United States Letters Patent on August 24, 2006 (Serial No. 11/509,063); and

WHEREAS, Stanley Electric Co., Ltd., a corporation of Japan, whose post office address is 2-9-13, Nakameguro, Meguro-ku, Tokyo, Japan, (hereinafter referred to as Stanley Electric), Tohoku University, a university of Japan, whose post office address is 1-1, Katahira 2-chome, Aoba-ku, Sendai-shi, Miyagi 9808577 (hereinafter referred to as Tohoku University), and Tokyo Denpa Co., Ltd., a corporation of Japan, whose post office address is 5-6-11, Chuo Ota-ku, Tokyo, Japan (hereinafter referred to as Tokyo Denpa) (Stanley Electric, Tohoku University, and Tokyo Denpa are collectively referred to as Assignee hereinafter) are desirous of securing collectively the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from Assignee is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto Stanley Electric, its lawful successors and assigns, 35 % of MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; further, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto Tohoku University, its lawful successors and assigns, 30 % of MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and further, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto Tokyo Denpa, its lawful successors and assigns, 35 % of MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.

IN TESTIMONY WHEREOF, I/WE have hereunto set our hand(s).

<b>Full Name of Sole or First Assignor</b> Hiroyuki KATO	Assignor's Signature <i>Hiroyuki Kato</i>	Date January 19, 2007
Address: c/o Stanley Electric Co., Ltd., 2-9-13, Nakameguro, Meguro-ku, Tokyo, Japan		Citizenship Japan
<b>Full Name of Second Assignor</b> Michihiro SANO	Assignor's Signature <i>Michihiro Sano</i>	Date January 19, 2007
Address: c/o Stanley Electric Co., Ltd., 2-9-13, Nakameguro, Meguro-ku, Tokyo, Japan		Citizenship Japan
Names of additional inventors attached <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No		

<b>Full Name of Third Assignor</b> Katsumi MAEDA	<b>Assignor's Signature</b> <i>Katsumi Maeda</i>	<b>Date</b> January 24, 2007
<b>Address:</b> 5-6-11, Chuo Ota-ku, Tokyo, Japan		<b>Citizenship</b> Japan
<b>Full Name of Fourth Assignor</b> Hiroshi YONEYAMA	<b>Assignor's Signature</b> <i>Hiroshi Yoneyama</i>	<b>Date</b> January 29, 2007
<b>Address:</b> 430 Oaza Hakoishi, Tamamura-cho, Sawa-gun, Gunma, Japan		<b>Citizenship</b> Japan
<b>Full Name of Fifth Assignor</b> Takafumi YAO	<b>Assignor's Signature</b> <i>Takafumi Yao</i>	<b>Date</b> February 6, 2007
<b>Address:</b> c/o Tohoku University, 1-1, Katahira 2-chome, Aoba-ku, Sendai-shi, Miyagi 9808577, Japan		<b>Citizenship</b> Japan
<b>Full Name of Sixth Assignor</b> Meoung Whan CHO	<b>Assignor's Signature</b> <i>Meoung Whan Cho</i>	<b>Date</b> February 6, 2007
<b>Address:</b> c/o Tohoku University, 1-1, Katahira 2-chome, Aoba-ku, Sendai-shi, Miyagi 9808577, Japan		<b>Citizenship</b> Korea
<b>Names of additional inventors attached</b> <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No		